

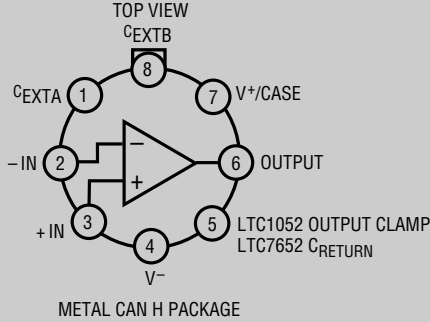
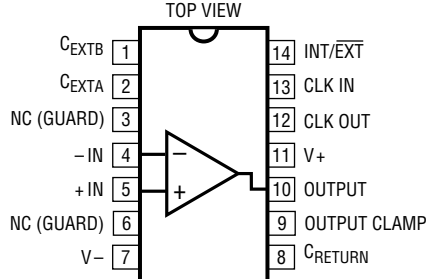
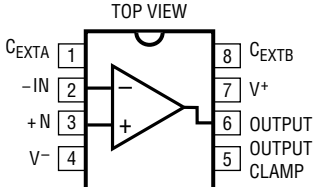
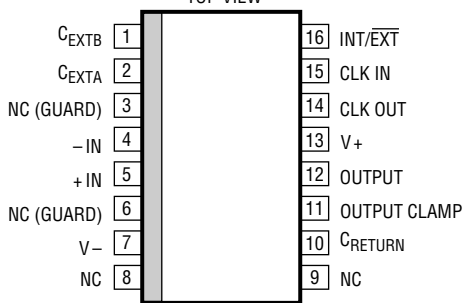
LTC1052/LTC7652

ABSOLUTE MAXIMUM RATINGS (Notes 1 and 2)

Total Supply Voltage (V^+ to V^-) 18V
 Input Voltage ($V^+ + 0.3V$) to ($V^- - 0.3V$)
 Output Short Circuit Duration Indefinite
 Storage Temperature Range -55°C to 150°C

Operating Temperature Range
 LTC1052C/LTC7652C -40°C to 85°C
 LTC1052M (**OBSOLETE**) -55°C to 125°C
 Lead Temperature (Soldering, 10 sec) 300°C

PACKAGE/ORDER INFORMATION

 METAL CAN H PACKAGE OBSOLETE PACKAGE Consider the N8 Package for Alternate Source		 N PACKAGE, 14-LEAD CERDIP $T_{JMAX} = 110^\circ\text{C}$, $\theta_{JA} = 130^\circ\text{C/W}$ J PACKAGE, 14-LEAD CERDIP OBSOLETE PACKAGE Consider the N14 Package for Alternate Source	
ORDER PART NUMBER	REPLACES	ORDER PART NUMBER	REPLACES
LTC7652CH	ICL7652CTV ICL7652ITV ICL7650CTV-1 ICL7650ITV-1	LTC1052CN	ICL7652CPD ICL7650CPD
LTC1052CH	ICL7650CTV ICL7650ITV	LTC1052CJ	ICL7652IJD ICL7650IJD
LTC1052MH	ICL7650MTV	LTC1052MJ	ICL7650MJD
 N8 PACKAGE 8-LEAD PDIP $T_{JMAX} = 110^\circ\text{C}$, $\theta_{JA} = 150^\circ\text{C/W}$ J8 PACKAGE, 8-LEAD CERDIP OBSOLETE PACKAGE Consider the N8 Package for Alternate Source		 SW PACKAGE 16-LEAD PLASTIC (WIDE) SO $T_{JMAX} = 110^\circ\text{C}$, $\theta_{JA} = 150^\circ\text{C/W}$	
ORDER PART NUMBER	REPLACES	ORDER PART NUMBER	REPLACES
LTC1052CN8	ICL7650CPA	LTC1052CSW	LTC1052CS
LTC1052CJ8	ICL7650IJA		
LTC1052MJ8			

Consult LTC Marketing for parts specified with wider operating temperature ranges.

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ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at $T_A = 25^\circ\text{C}$. $V_S = \pm 5\text{V}$, test circuit TC1, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	LTC1052M			LTC1052C/LTC7652C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{OS}	Input Offset Voltage	(Note 3)		± 0.5	± 5		± 0.5	± 5	μV
$\Delta V_{OS}/\Delta\text{Temp}$	Average Input Offset Drift	(Note 3)	●	± 0.01	± 0.05		± 0.01	± 0.05	$\mu\text{V}/^\circ\text{C}$
$\Delta V_{OS}/\Delta\text{Time}$	Long-Term Offset Voltage Stability			100			100		$\text{nV}/\sqrt{\text{Month}}$
I_{OS}	Input Offset Current		●	± 30	± 90 ± 2000		± 30	± 90 ± 350	pA pA
I_B	Input Bias Current		●	± 1	± 30 ± 1000		± 1	± 30 ± 175	pA pA
$e_{n\text{P-P}}$	Input Noise Voltage	$R_S = 100\Omega$, DC to 10Hz, TC3 $R_S = 100\Omega$, DC to 1Hz, TC3		1.5 0.5			1.5 0.5		$\mu\text{V}_{\text{P-P}}$ $\mu\text{V}_{\text{P-P}}$
I_n	Input Noise Current	$f = 10\text{Hz}$ (Note 5)		0.6			0.6		$\text{fA}/\sqrt{\text{Hz}}$
CMRR	Common Mode Rejection Ratio	$V_{\text{CM}} = V^-$ to 2.7V	●	120	140		120	140	dB
PSRR	Power Supply Rejection Ratio	$V_{\text{SUPPLY}} = \pm 2.375\text{V}$ to $\pm 8\text{V}$	●	120	150		120	150	dB
A_{VOL}	Large-Signal Voltage Gain	$R_L = 10\text{k}$, $V_{\text{OUT}} = \pm 4\text{V}$	●	120	150		120	150	dB
V_{OUT}	Maximum Output Voltage Swing (Note 4)	$R_L = 10\text{k}$ $R_L = 100\text{k}$	●	± 4.7	± 4.85 ± 4.95		± 4.7	± 4.85 ± 4.95	V V
SR	Slew Rate	$R_L = 10\text{k}$, $C_L = 50\text{pF}$		4			4		$\text{V}/\mu\text{s}$
GBW	Gain Bandwidth Product			1.2			1.2		MHz
I_S	Supply Current	No Load	●	1.7	2.0 3.0		1.7	2.0 3.0	mA mA
f_S	Internal Sampling Frequency			330			330		Hz
	Clamp On Current	$R_L = 100\text{k}$	●	25	100		25	100	μA
	Clamp Off Current	$-4\text{V} < V_{\text{OUT}} < 4\text{V}$	●	10	100 2		10	100 1	pA nA

Note 1: Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Note 2: Connecting any terminal to voltages greater than V^+ , or less than V^- , may cause destructive latch-up. It is recommended that no sources operating from external supplies be applied prior to power-up of the LTC1052/LTC7652.

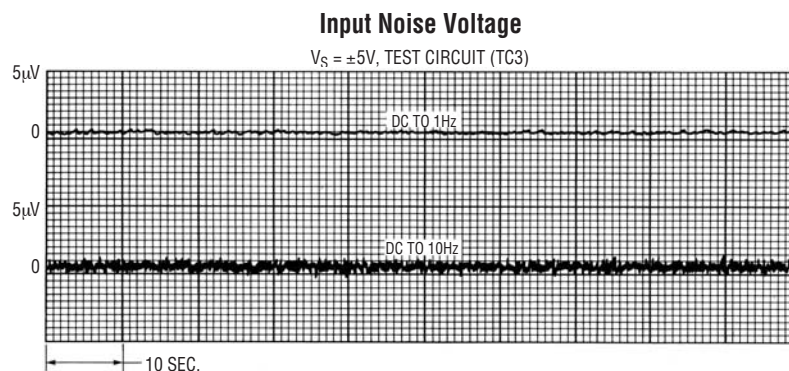
Note 3: These parameters are guaranteed by design. Thermocouple effects preclude measurement of the voltage levels in high speed automatic

testing. V_{OS} is measured to a limit determined by test equipment capability. Voltages on C_{EXTA} and C_{EXTB} , A_{VOL} , CMRR and PSRR are measured to insure proper operation of the nulling loop to ensure meeting the V_{OS} and V_{OS} drift specifications. See Package-Induced V_{OS} in the Applications Information section.

Note 4: Output clamp not connected.

Note 5: Current noise is calculated from the formula: $i_n = (2q I_B)^{1/2}$, where $q = 1.6 \cdot 10^{-19}$ coulomb.

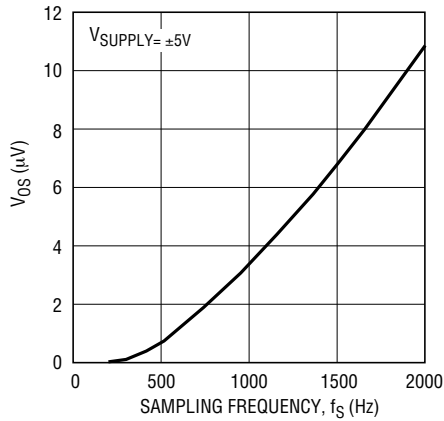
TYPICAL PERFORMANCE CHARACTERISTICS



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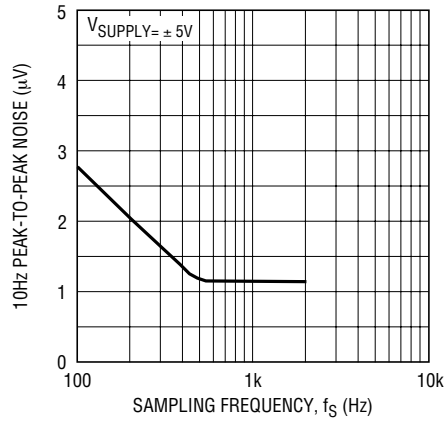
TYPICAL PERFORMANCE CHARACTERISTICS

Offset Voltage vs Sampling Frequency



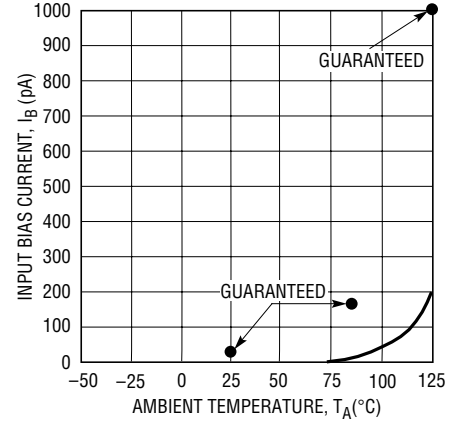
LTC1052/7652 • TPC01

10Hz_{p-p} Noise vs Sampling Frequency



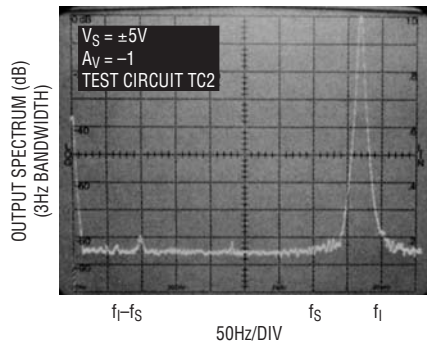
LTC1052/7652 • TPC02

Input Bias Current vs Temperature

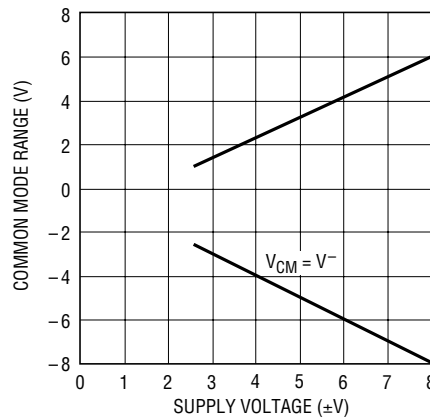


LTC1052/7652 • TPC03

Aliasing Error

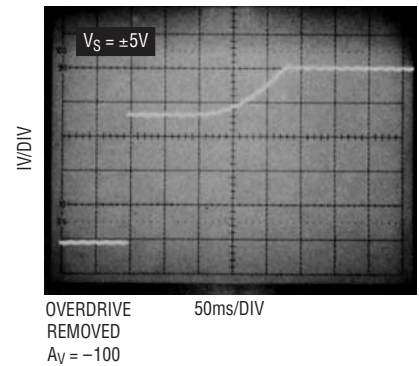


Common Mode Input Range vs Supply Voltage

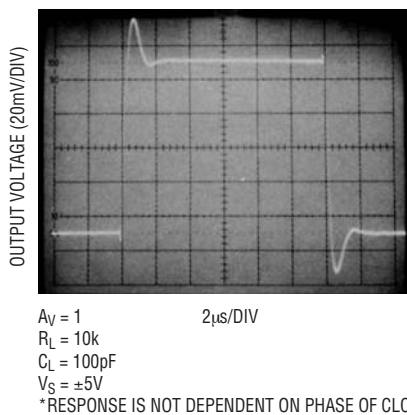


LTC1052/7652 • TPC04

Overload Recovery (Output Clamp Not Used)

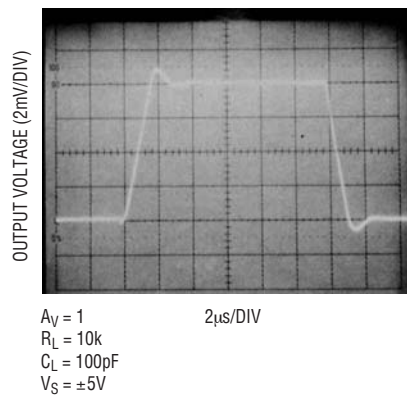


Small-Signal Transient Response*

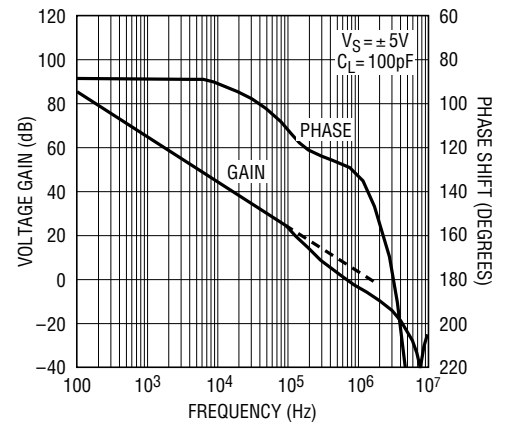


*RESPONSE IS NOT DEPENDENT ON PHASE OF CLOCK

Large-Signal Transient Response*

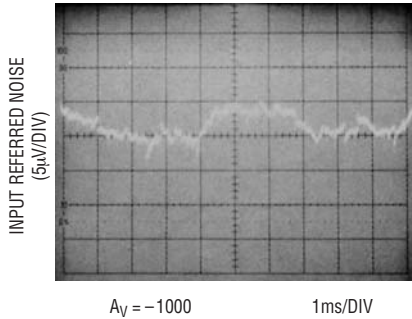
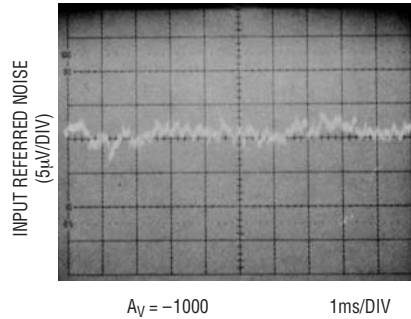


Gain Phase vs Frequency

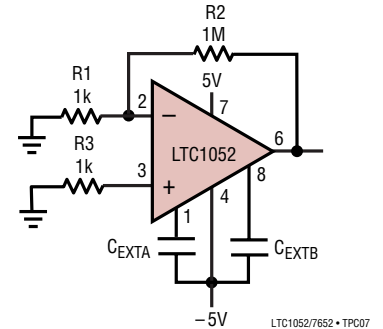


LTC1052/LTC7652 • TPC06

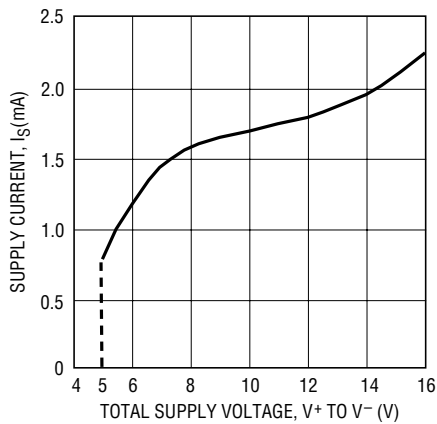
TYPICAL PERFORMANCE CHARACTERISTICS

Broadband Noise, $C_{EXT} = 0.1\mu F$ Broadband Noise, $C_{EXT} = 1.0\mu F$ 

Broadband Noise Test Circuit (TC2)

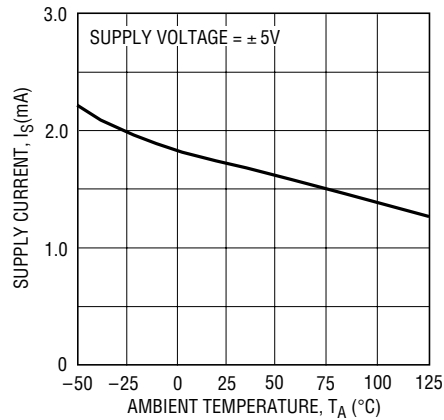


Supply Current vs Supply Voltage



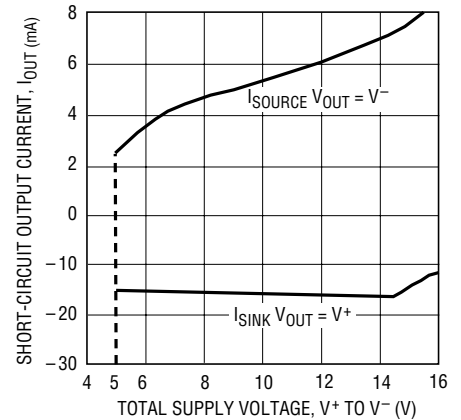
LTC1052/LTC7652 • TPC08

Supply Current vs Temperature



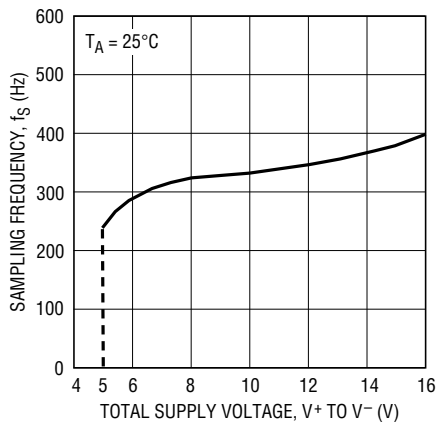
LTC1052/LTC7652 • TPC09

Output Short-Circuit Current vs Supply Voltage



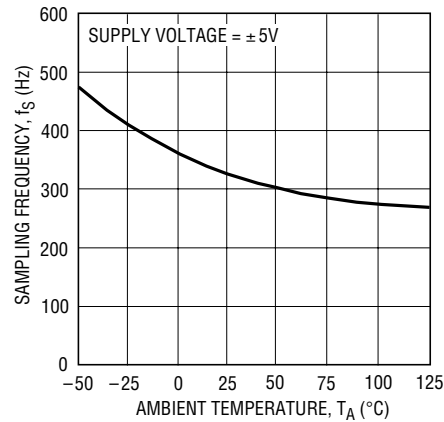
LTC1052/LTC7652 • TPC10

Sampling Frequency vs Voltage



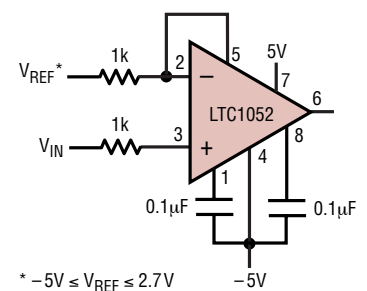
LTC1052/LTC7652 • TPC11

Sampling Frequency vs Temperature



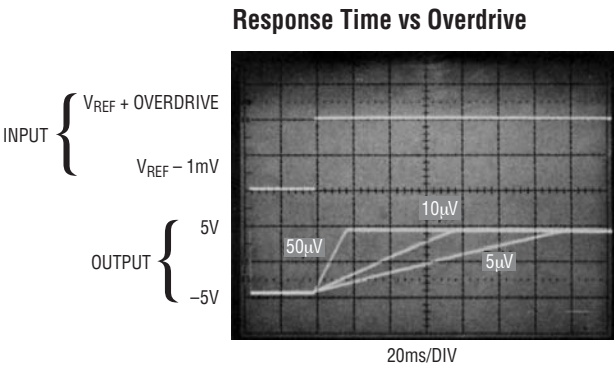
LTC1052/LTC7652 • TPC12

Comparator Operation



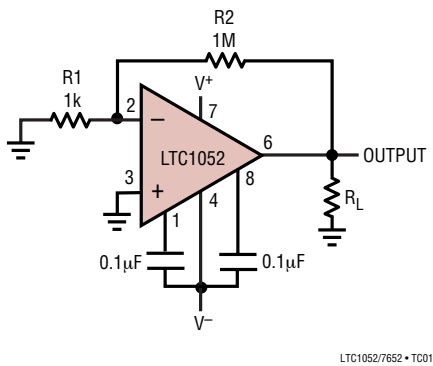
LTC1052/7652 • TPC13

TYPICAL PERFORMANCE CHARACTERISTICS



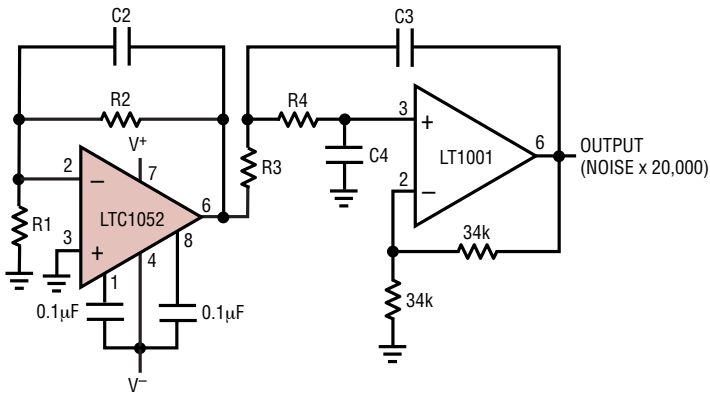
TEST CIRCUITS

Electrical Characteristics Test Circuit (TC1)



LTC1052/7652 • TC01

DC to 10Hz and DC to 1Hz Noise Test Circuit (TC3)



BANDWIDTH	R1	R2	R3	R4	C2	C3	C4
10Hz	16.2Ω	162k	16.2k	16.2k	0.1µF	1.0µF	1.0µF
1Hz	16.2Ω	162k	162k	162k	1.0µF	1.0µF	1.0µF

LTC1052/7652 • TC02

THEORY OF OPERATION

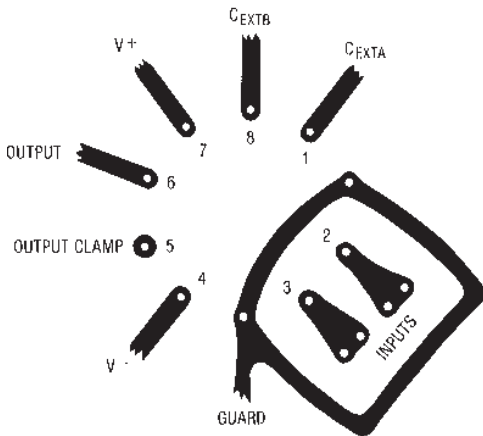
DC OPERATION

The shaded portion of the LTC1052 block diagram (Figure 1a) entirely determines the amplifier's DC characteristics. During the auto zero portion of the cycle, the g_{m1} inputs are shorted together and a feedback path is closed around the input stage to null its offset. Switch S2 and capacitor C_{EXTA} act as a sample-and-hold to store the nulling voltage during the next step—the sampling cycle. In the sampling cycle, the zeroed amplifier is used to amplify the differential input voltage. Switch S2 connects the amplified input voltage to C_{EXTB} and the output gain

stage. C_{EXTB} and S2 act as a sample-and-hold to store the amplified input signal during the auto zero cycle. By switching between these two states at a frequency much higher than the signal frequency, a continuous output results. Notice that during the auto zero cycle the g_{m1} inputs are not only shorted together, but are also shorted to the inverting input. This forces nulling with the common mode voltage present and accounts for the extremely high CMRR of the LTC1052. In the same fashion, variations in

APPLICATIONS INFORMATION

connections, to the inverting input. Guarding both sides of the printed circuit board is required. Bulk leakage reduction depends on the guard ring width.



Microvolts

Thermocouple effects must be considered if the LTC1052's ultralow drift is to be fully utilized. Any connection of dissimilar metals forms a thermoelectric junction producing an electric potential which varies with temperature (Seebeck effect). As temperature sensors, thermocouples exploit this phenomenon to produce useful information. In low drift amplifier circuits the effect is a primary source of error.

Connectors, switches, relay contacts, sockets, resistors, solder, and even copper wire are all candidates for thermal EMF generation. Junctions of copper wire from different manufacturers can generate thermal EMFs of $200\text{nV}/^\circ\text{C}$ —4 times the maximum drift specification of the LTC1052. The copper/kovar junction, formed when wire or printed circuit traces contact a package lead, has a thermal EMF of approximately $35\mu\text{V}/^\circ\text{C}$ —700 times the maximum drift specification of the LTC1052.

Minimizing thermal EMF-induced errors is possible if judicious attention is given to circuit board layout and component selection. It is good practice to minimize the number of junctions in the amplifier's input signal path. Avoid connectors, sockets, switches and relays where possible. In instances where this is not possible, attempt to balance the number and type of junctions so that differential cancellation occurs. Doing this may involve deliberately introducing junctions to offset unavoidable junctions.

Figure 2 is an example of the introduction of an unnecessary resistor to promote differential thermal balance. Maintaining compensating junctions in close physical proximity will keep them at the same temperature and reduce thermal EMF errors.

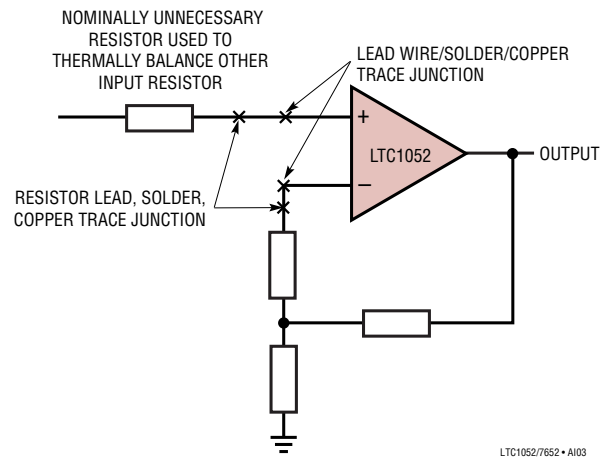


Figure 2

When connectors, switches, relays and/or sockets are necessary they should be selected for low thermal EMF activity. The same techniques of thermally balancing and coupling the matching junctions are effective in reducing the thermal EMF errors of these components.

Resistors are another source of thermal EMF errors. Table 1 shows the thermal EMF generated for different resistors. The temperature gradient across the resistor is important, not the ambient temperature. There are two junctions formed at each end of the resistor and if these junctions are at the same temperature, their thermal EMFs will cancel each other. The thermal EMF numbers are approximate and vary with resistor value. High values give higher thermal EMF.

Table 1. Resistor Thermal EMF

RESISTOR TYPE	THERMAL EMF/ $^\circ\text{C}$ GRADIENT
Tin Oxide	$\sim\text{mV}/^\circ\text{C}$
Carbon Composition	$\sim 450\mu\text{V}/^\circ\text{C}$
Metal Film	$\sim 20\mu\text{V}/^\circ\text{C}$
Wire Wound	$\sim 2\mu\text{V}/^\circ\text{C}$ $\sim 2\mu\text{V}/^\circ\text{C}$
Evenohm	
Manganin	

APPLICATIONS INFORMATION

When all of these errors are considered, it may seem impossible to take advantage of the extremely low drift specifications of the LTC1052. To show that this is not the case, examine the temperature test circuit of Figure 3. The lead lengths of the resistors connected to the amplifier's inputs are identical. The thermal capacity and thermal resistance each input sees is balanced because of the symmetrical connection of resistors and their identical size. Thermal EMF-induced shifts are equal in phase and amplitude, thus cancellation occurs.

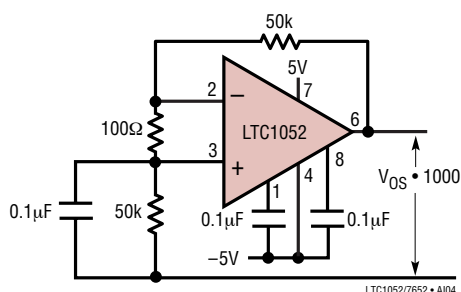


Figure 3. Offset Drift Test Circuit

Figure 4 shows the response of this circuit under temperature transient conditions. Metal film resistors and an 8-pin DIP socket were used. Care was taken in the construction to thermally balance the inputs to the amplifier. The units were placed in an oven and allowed to stabilize at 25°C. The recording was started and after 100 seconds the oven, preset to 125°C, was switched on. The test was first performed on an 8-pin plastic package and then was repeated for a TO-5 package plugged into the same test board. It is significant that the change in V_{OS} , even under these severe thermal transient conditions, is quite good. As temperature stabilizes, note that the steady-state change of V_{OS} is well within the maximum $\pm 0.05\mu\text{V}/^\circ\text{C}$ drift specification.

Very slight air currents can still affect even this arrangement. Figure 5 shows strip charts of output noise both with the circuit covered and with no cover in "still" air. This data illustrates why it is often prudent to enclose the LTC1052 and its attendant components inside some form of thermal baffle.

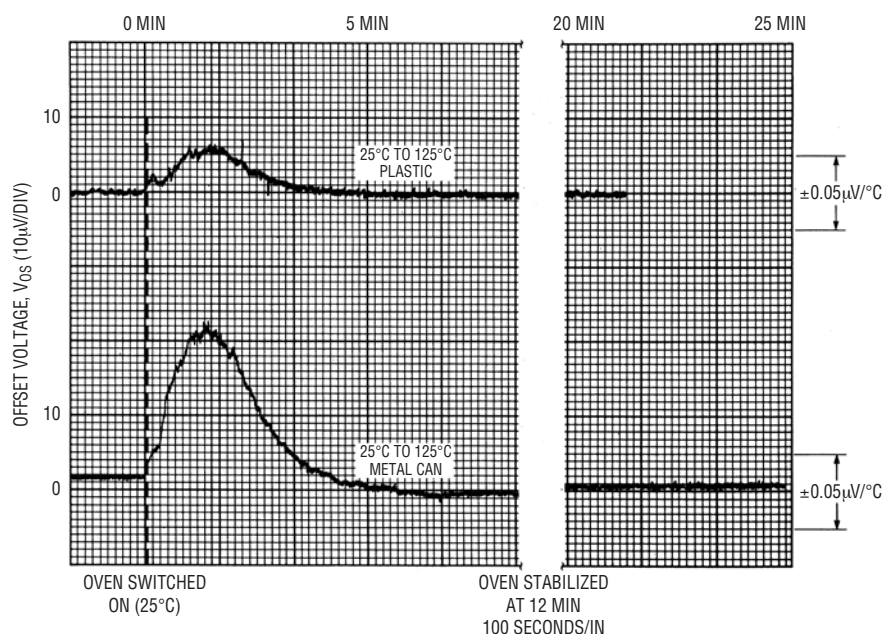


Figure 4. Transient Response of Offset Drift Test Circuit with 100°C Temperature Step

APPLICATIONS INFORMATION

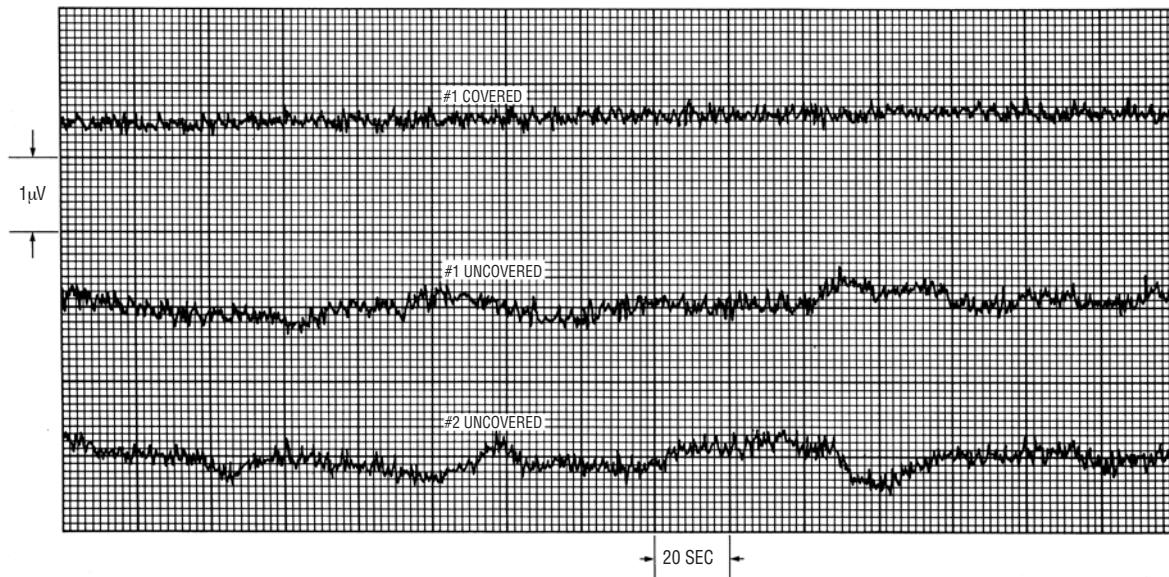


Figure 5. DC to 1Hz (Test Circuit TC3)

PACKAGE-INDUCED OFFSET VOLTAGE

Since the LTC1052 is constantly fixing its own offset, it may be asked why there is any error at all, even under transient temperature conditions. The answer is simple. The LTC1052 can only fix offsets inside its own nulling loop. There are many thermal junctions outside this loop that cannot be distinguished from legitimate signals.

Some have been discussed previously, but the package thermal EMF effects are an important source of errors.

Notice the difference in the thermal response curves of Figure 4. This can only be attributed to the package since everything else is identical. In fact, the V_{OS} specification is set by the package-induced warm-up drift, not by the LTC1052. TO-99 metal cans exhibit the worst warm-up drift and Linear Technology sample tests TO-99 lots to minimize this problem.

Two things make 100% screening costly: (1) The extreme precision required on the LTC1052 and (2) the thermal time constant of the package is 0.5 to 3 minutes, depending on package type. The first precludes the use of automatic handling equipment and the second takes a long time. Bench test equipment is available to 100% test for warmed-up drift if offsets of less than $\pm 5\mu\text{V}$ are required.

CLOCK

The LTC1052 has an internal clock, setting the nominal sampling frequency at 330Hz. On 8-pin devices, there is no way to control the clock externally. In some applications it may be desirable to control the sampling clock and this is the function of the 14-pin device.

CLK IN, CLK OUT and INT/ $\overline{\text{EXT}}$ are provided to accomplish this. With no external connection, an internal pull-up holds INT/ $\overline{\text{EXT}}$ at the V^+ supply and the 14-pin device self-oscillates at 330Hz. In this mode there is a signal on the CLK IN pin of 660Hz (2 times sampling frequency) with a 30% duty cycle. A divide-by-two drives the CLK OUT pin and sets the sampling frequency.

To use an external clock, connect INT/ $\overline{\text{EXT}}$ to V^- and the external clock to CLK IN. The logic threshold of CLK IN is 2.5V below the positive supply; this allows CMOS logic to drive it directly with logic supplies of V^+ and ground. CLK IN can be driven from V^+ to V^- if desired. The duty cycle of the external clock is not particularly critical but should be kept between 30% and 60%.

Capacitance between CLK IN and CLK OUT (pins 13 and 12) can cause the divide-by-two circuit to malfunction. To avoid this, keep this capacitance below 5pF.

APPLICATIONS INFORMATION

OUTPUT CLAMP

If the LTC1052 is driven into saturation, the nulling loop, attempting to force the differential input voltage to zero, will drive C_{EXTA} and C_{EXTB} to a supply rail. After the saturating drive is removed, the capacitors take a finite time to recover—this is the overload recovery time. The overload recovery is longest when the capacitors are driven to the negative rail (refer to Overload Recovery in the Typical Performance Characteristics section). The overload recovery time in this case is typically 225ms. In the opposite direction (i.e., C_{EXTA} and C_{EXTB} at positive rail), it is about ten times faster (25ms). The overload recovery time for the LTC1052 is much faster than competitive devices; however, if a faster overload recovery time is necessary, the output clamp function can be used.

When the output clamp is connected to the negative input it prevents the amplifier from saturating, thus keeping C_{EXTA} and C_{EXTB} at their nominal voltages. The output clamp is a switch that turns on when the output gets to

within approximately 1V of either supply rail. This switch is in parallel with the amplifier's feedback resistor. As the output moves closer to the rail, the switch on resistance decreases, reducing the closed loop gain. The output swing is reduced when the clamp function is used.

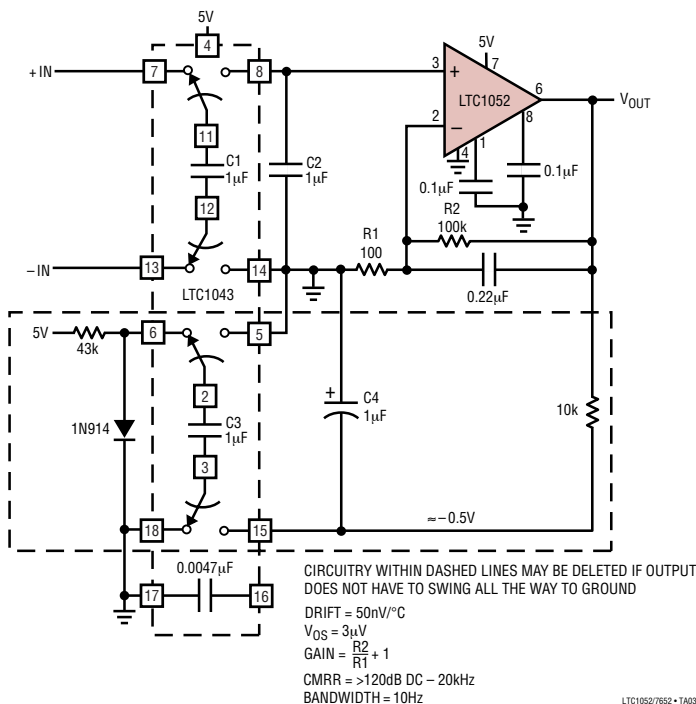
How much current the output clamp leaks when off is important because, when used, it is connected to the amplifier's negative input. Any current acts like input bias current and will degrade accuracy. At the other extreme, the maximum current the clamp conducts when on determines how much overdrive the clamp will take, and still keep the amplifier from saturating. Both of these numbers are guaranteed in the Electrical Characteristics section.

LOW SUPPLY OPERATION

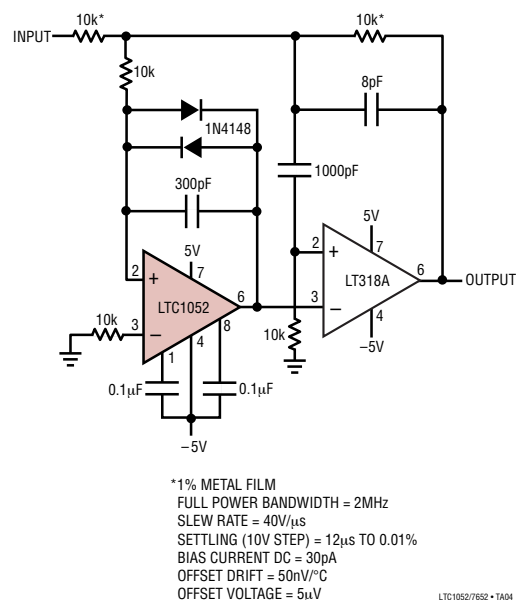
The minimum supply voltage for proper operation of the LTC1052 is typically 4.0V ($\pm 2.0V$). In single supply applications, PSRR is guaranteed down to 4.7V ($\pm 2.35V$). This assures proper operation down to the minimum TTL specified voltage of 4.75V.

TYPICAL APPLICATIONS

5V Powered Ultraprecision Instrumentation Amplifier

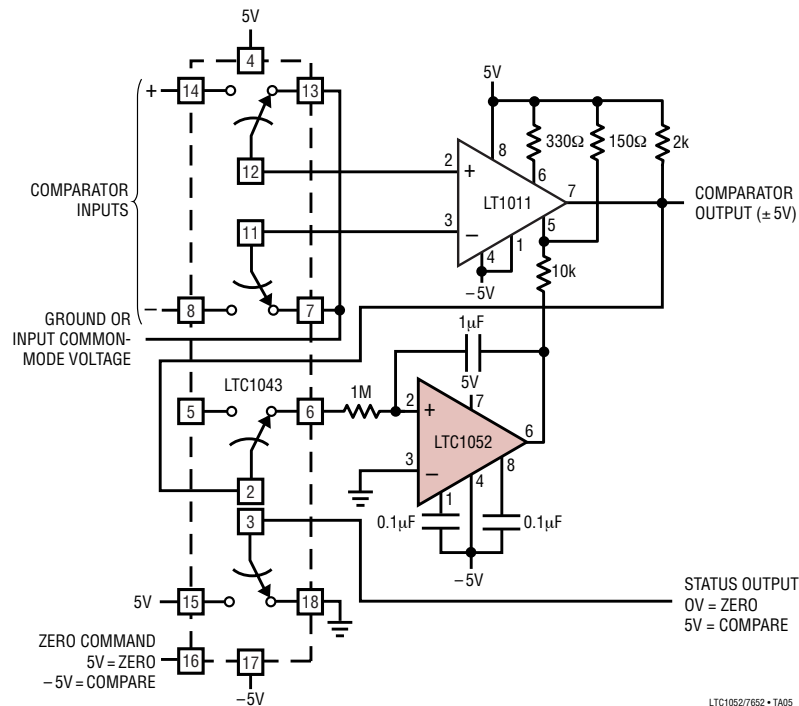


Fast Precision Inverter

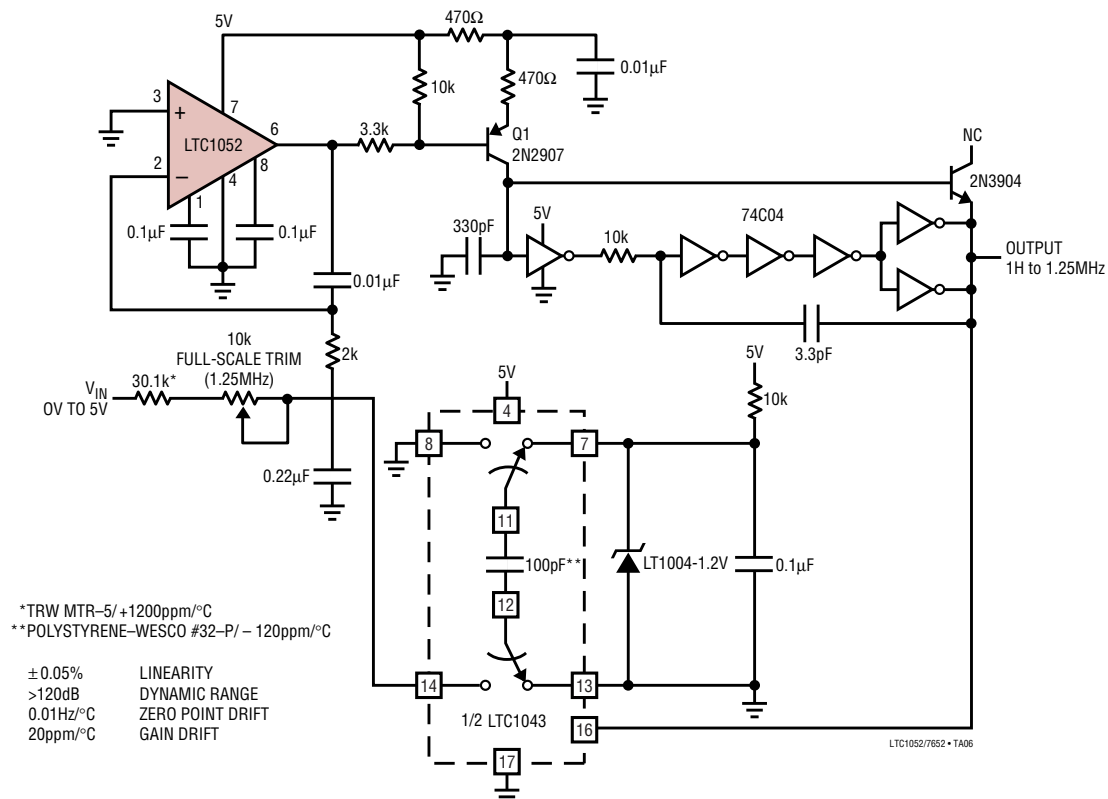


TYPICAL APPLICATIONS

Offset Stabilized Comparator

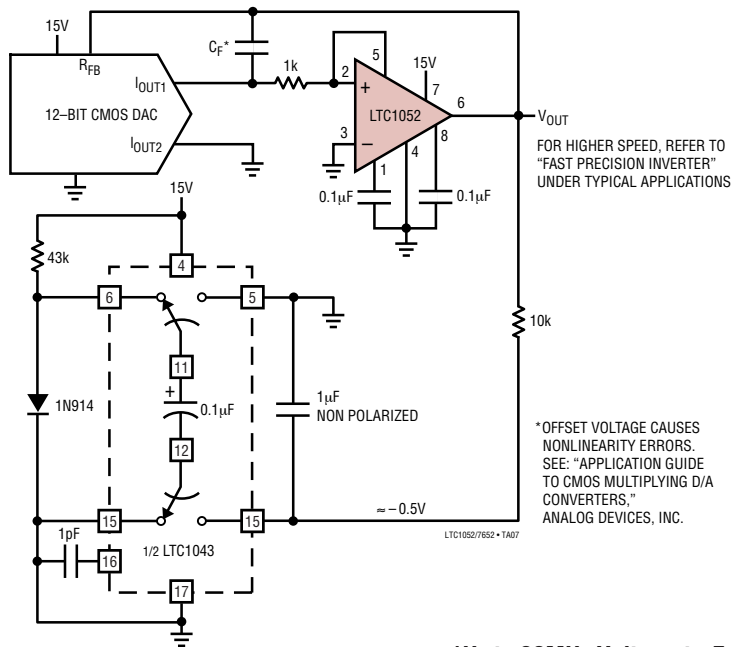


1HZ to 1.25MHz Voltage-to-Frequency Converter (5V Supply)

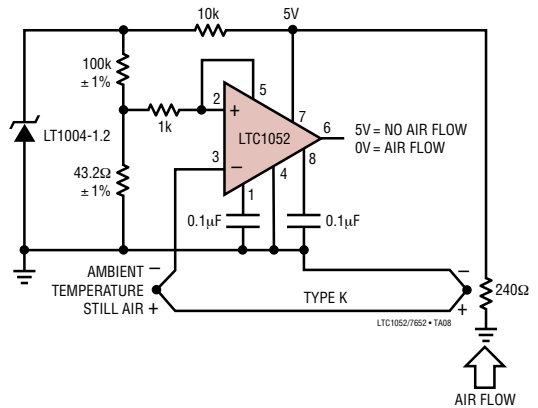


TYPICAL APPLICATIONS

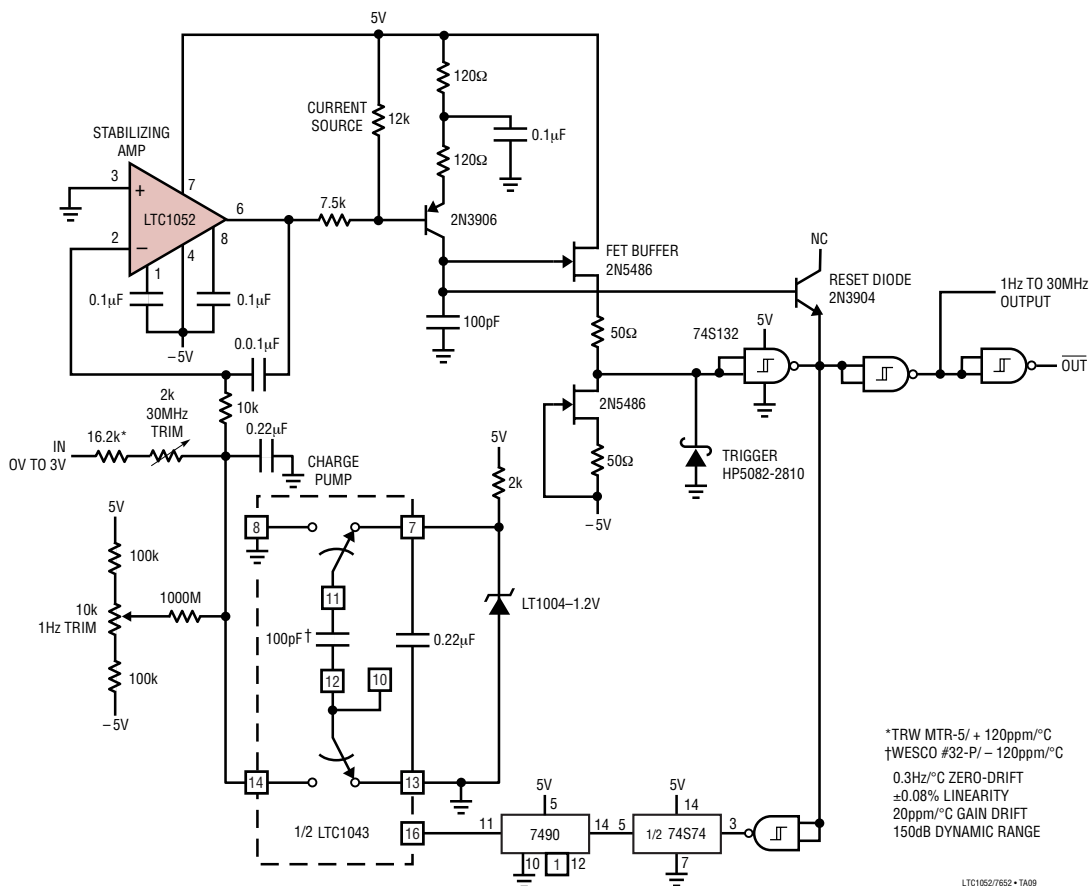
No V_{OS} Adjust* CMOS DAC Buffer—Single Supply



Air Flow Detector



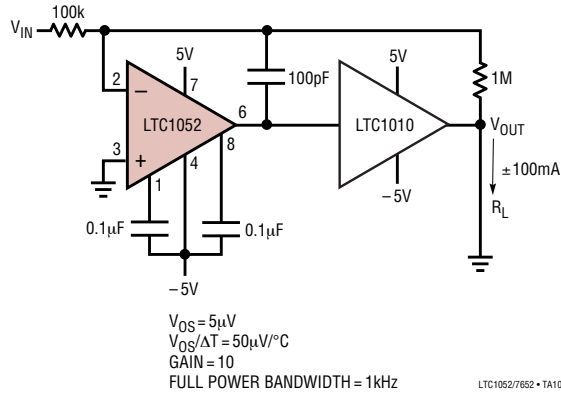
1Hz to 30MHz Voltage-to-Frequency Converter



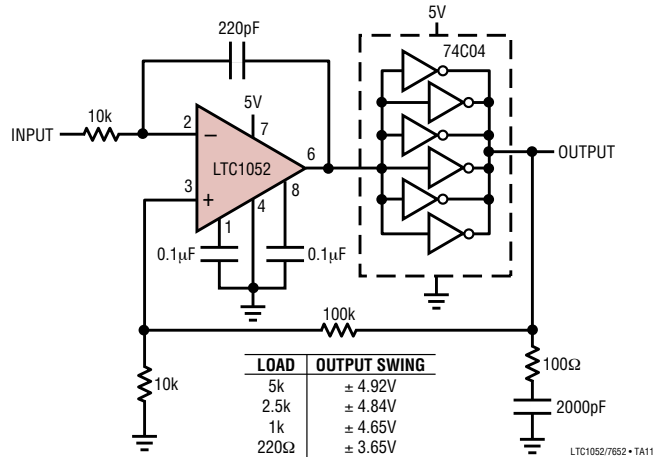
*TRW MTR-5/ + 120ppm/°C
 †WESCO #32-P/ - 120ppm/°C
 0.3Hz/°C ZERO-DRIFT
 ±0.08% LINEARITY
 20ppm/°C GAIN DRIFT
 150dB DYNAMIC RANGE

LTC1052/7652 • TA09

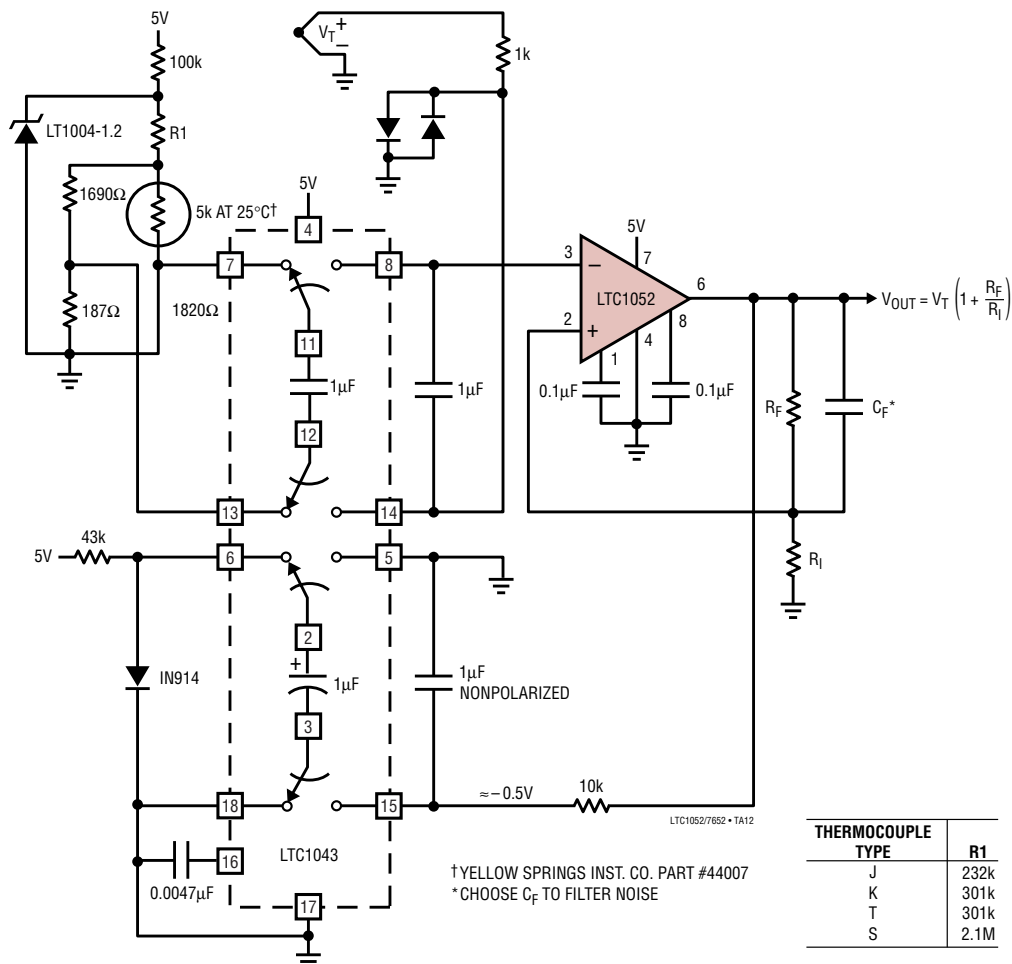
TYPICAL APPLICATIONS

 $\pm 100\text{mA}$ Output Drive

Increasing Output Current

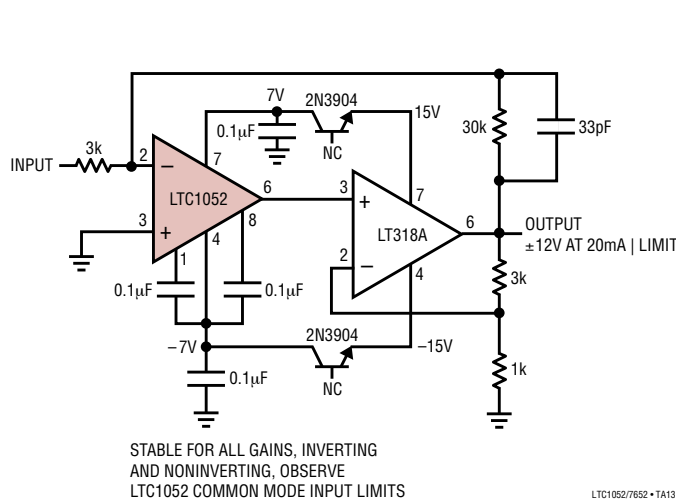


Single 5V Thermocouple Amplifier with Cold Junction Compensation



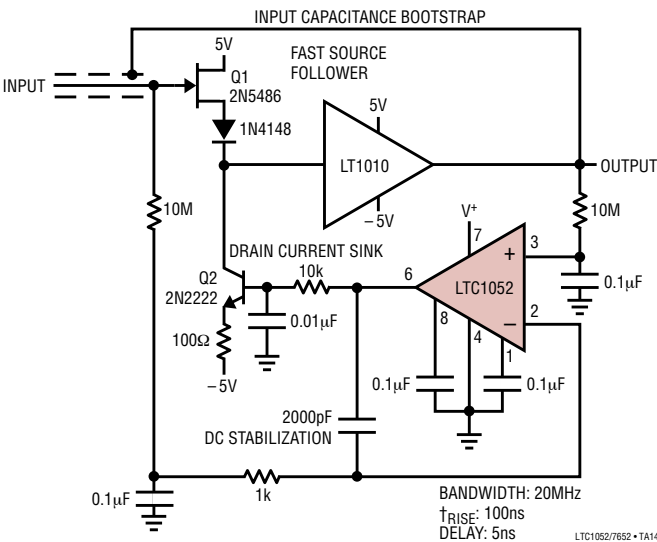
TYPICAL APPLICATIONS

Increasing Output Current and Voltage (V_{SUPPLY} = ±15V)



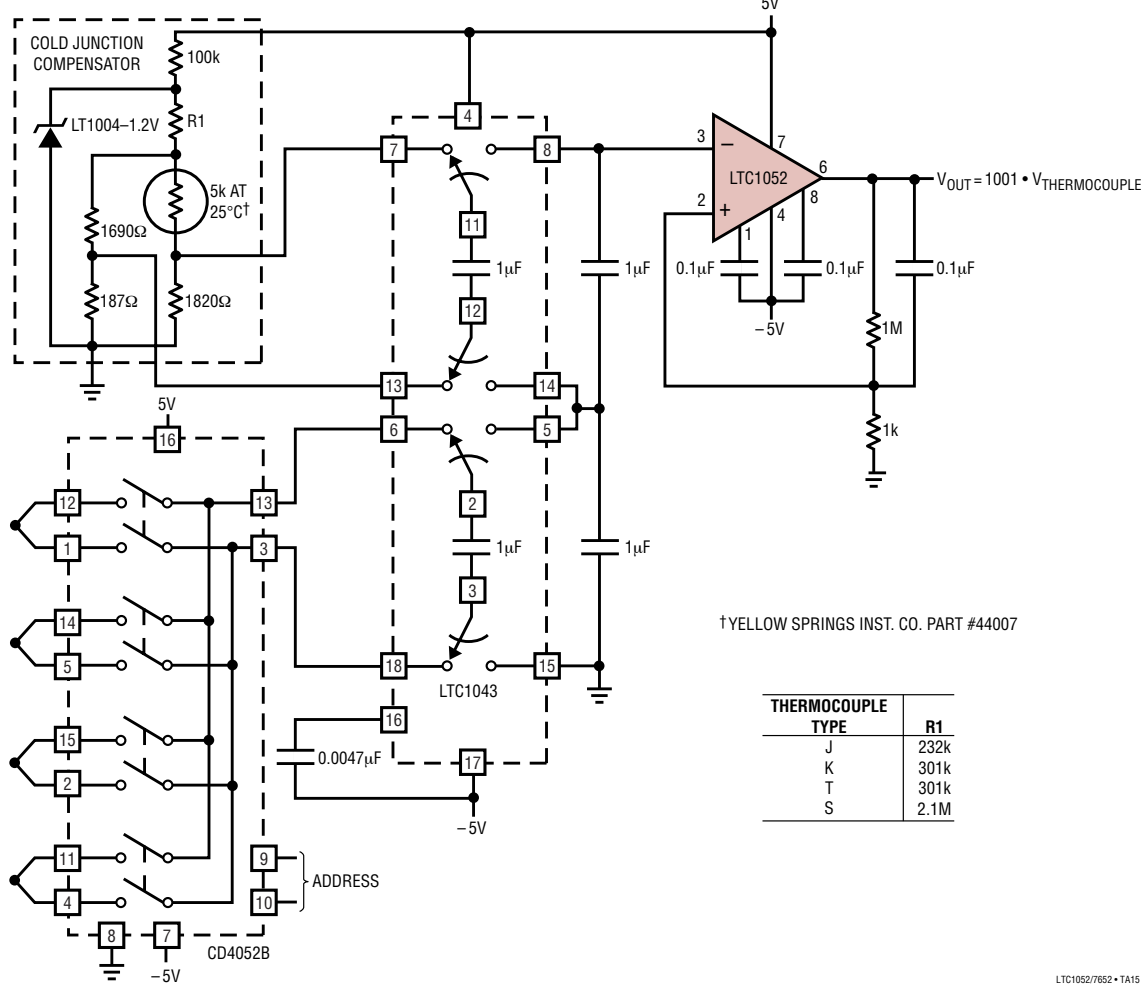
LTC1052/7652 • TA13

DC Stabilized FET Probe



LTC1052/7652 • TA14

Precision Multiplexed Differential Thermocouple Amplifier



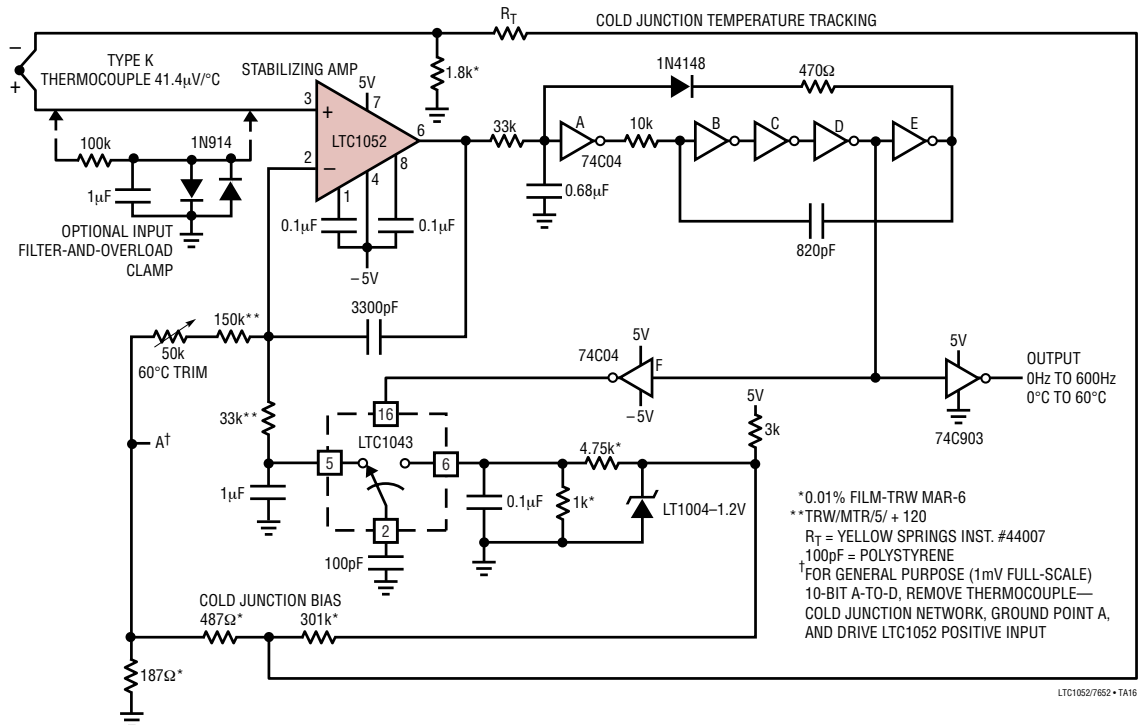
† YELLOW SPRINGS INST. CO. PART #44007

THERMOCOUPLE TYPE	R1
J	232k
K	301k
T	301k
S	2.1M

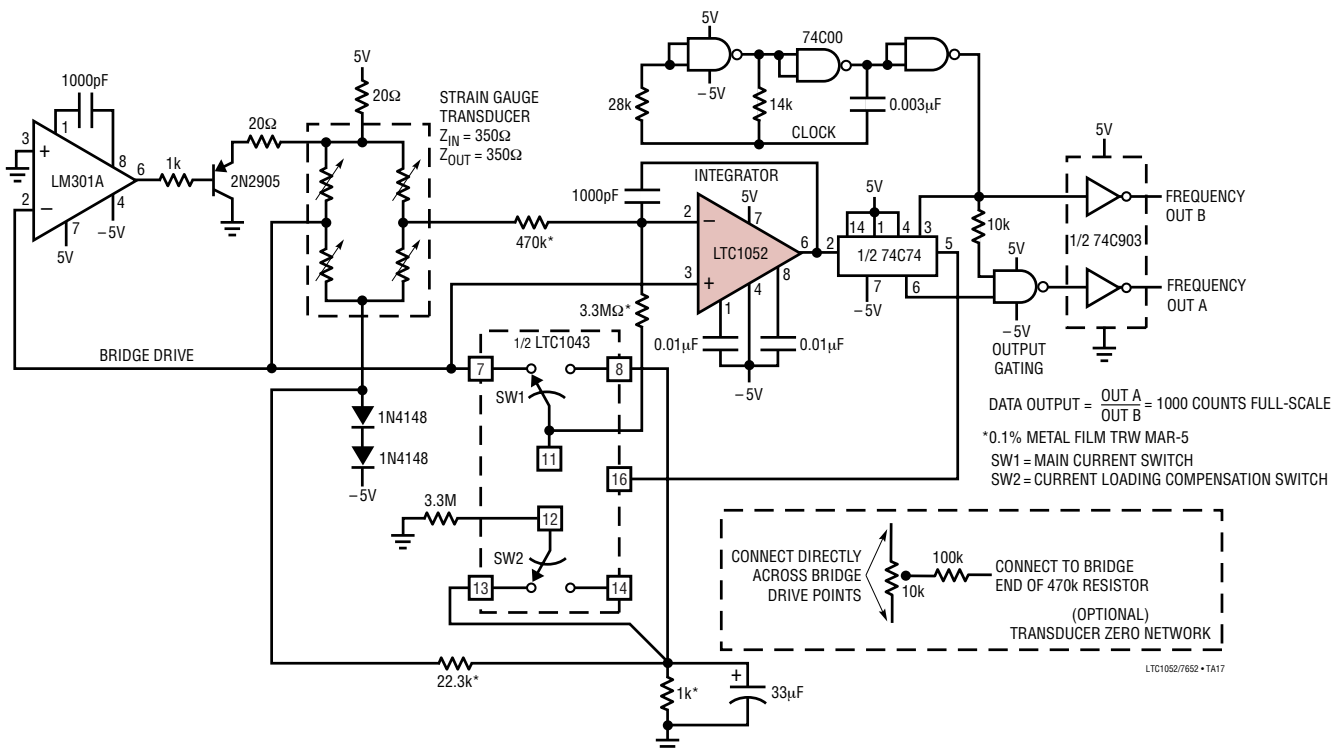
LTC1052/7652 • TA15

TYPICAL APPLICATIONS

Direct Thermocouple-to-Frequency Converter

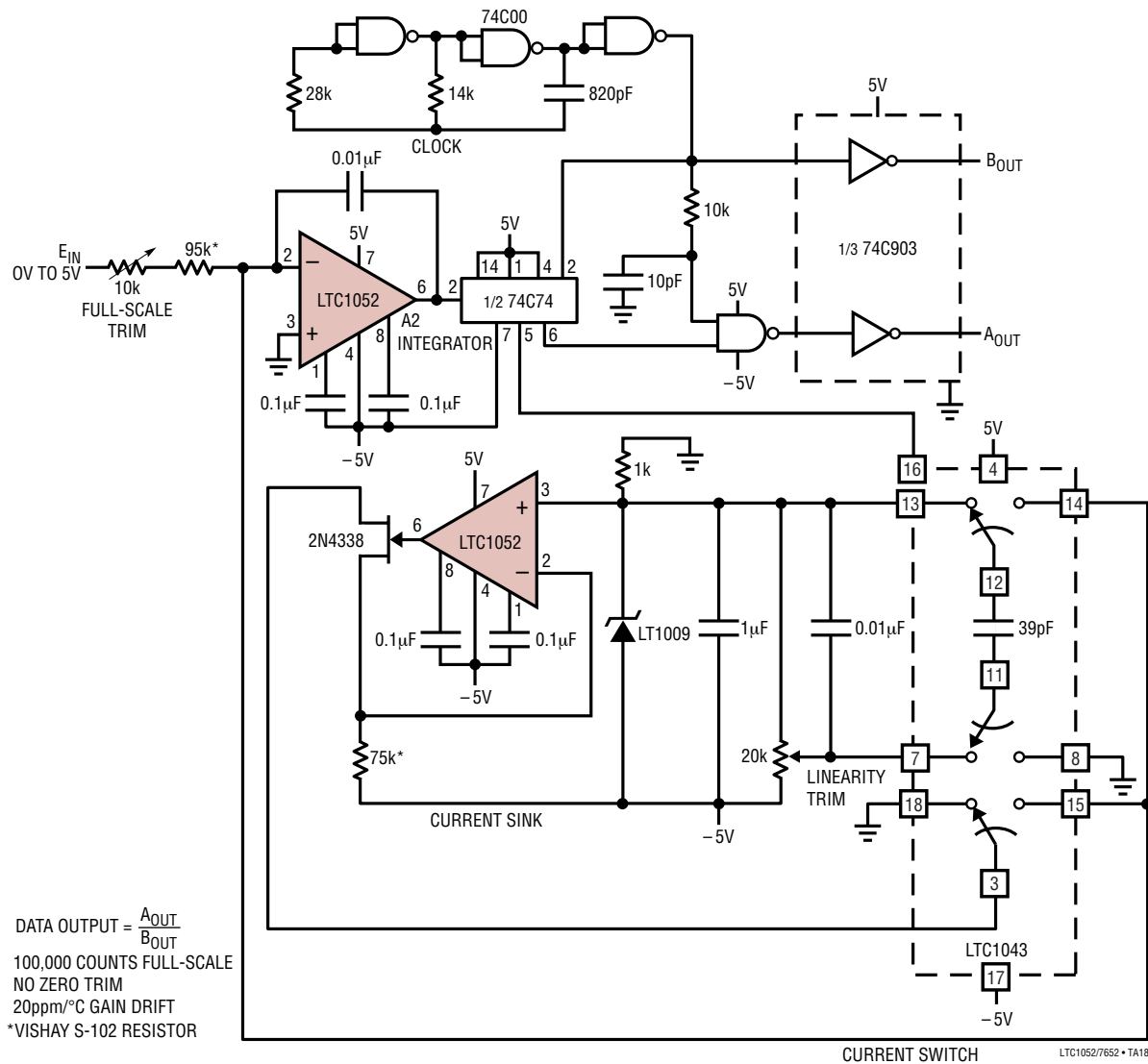


Direct 10-Bit Strain Gauge Digitizer

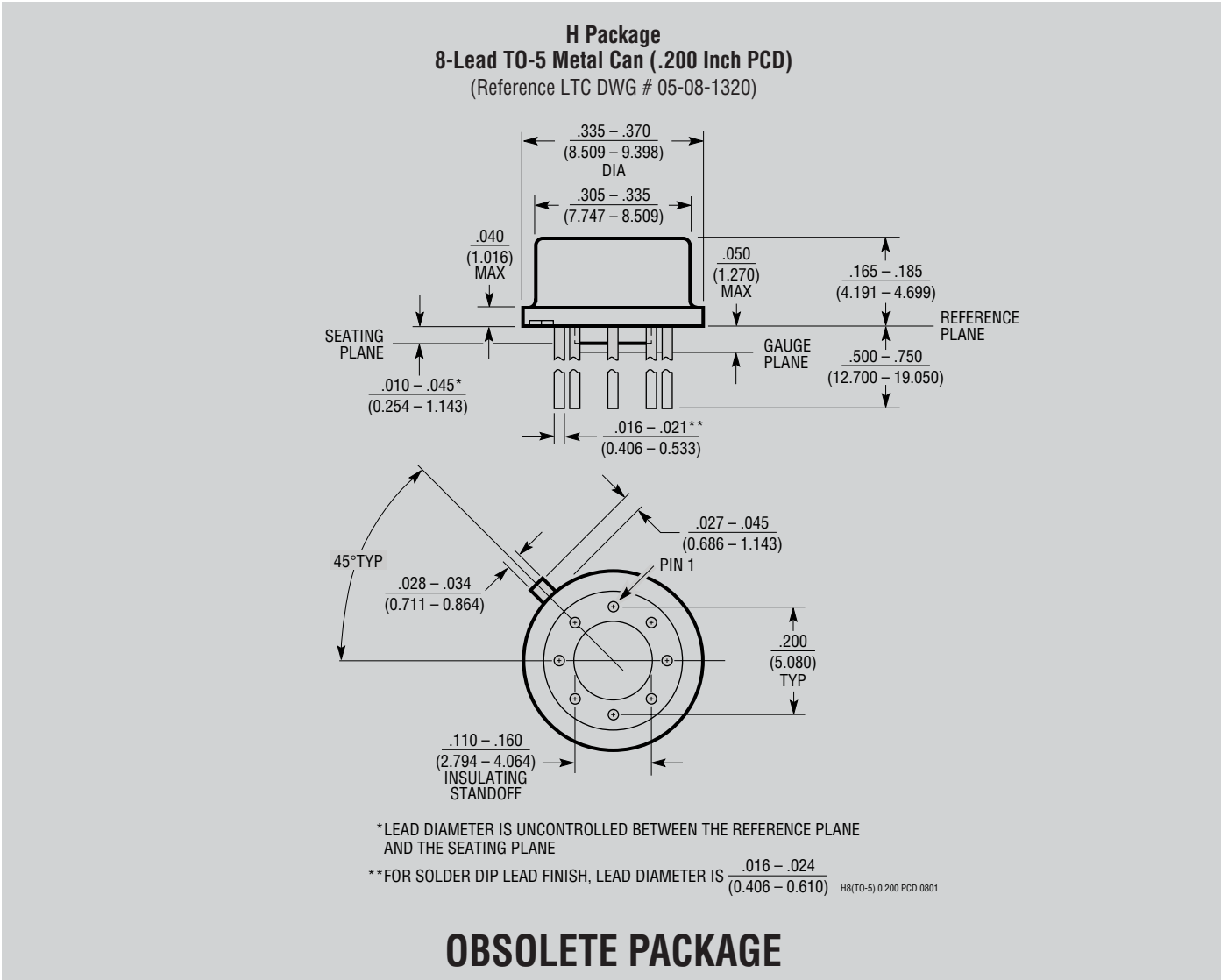


TYPICAL APPLICATIONS

16-Bit A/D Converter

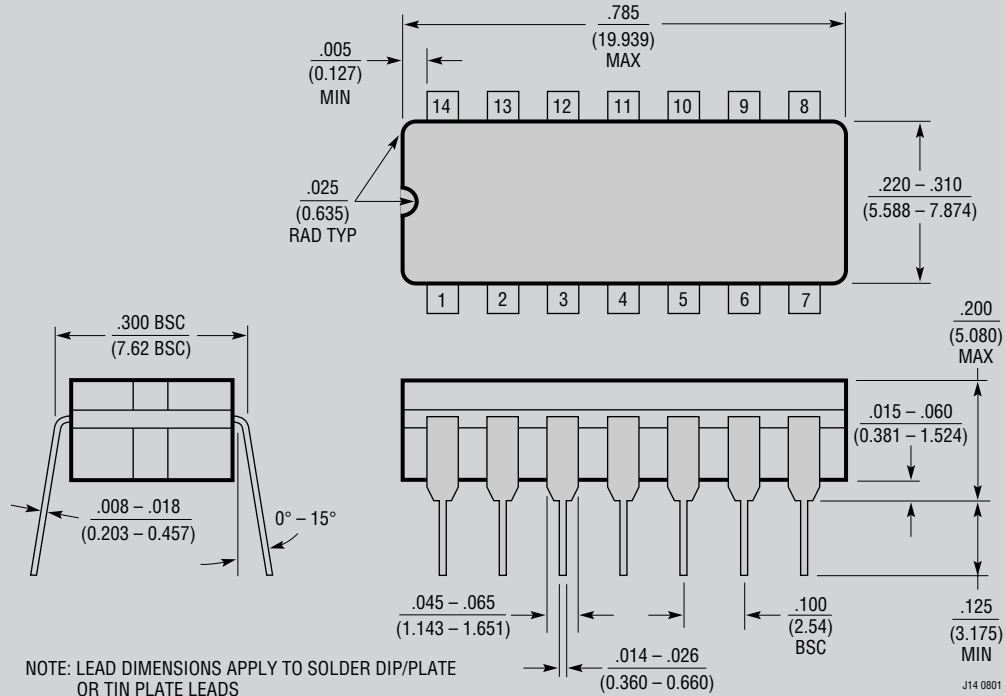


PACKAGE DESCRIPTION



PACKAGE DESCRIPTION

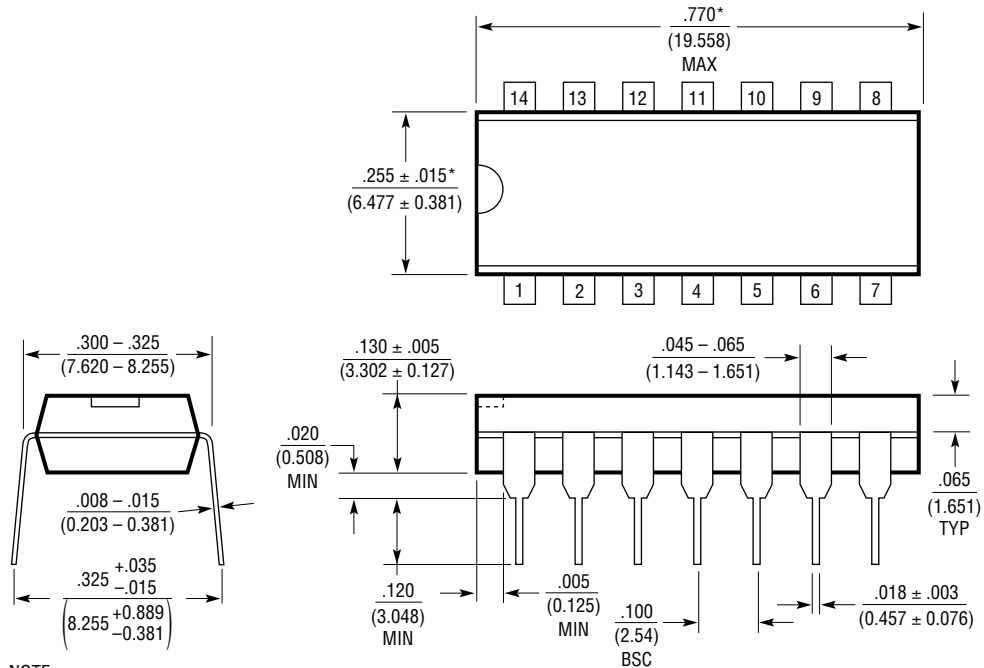
J Package
14-Lead Cerdip (Narrow .300 Inch, Hermetic)
 (Reference LTC DWG # 05-08-1110)



OBSOLETE PACKAGE

PACKAGE DESCRIPTION

N Package 14-Lead PDIP (Narrow .300 Inch) (Reference LTC DWG # 05-08-1510)



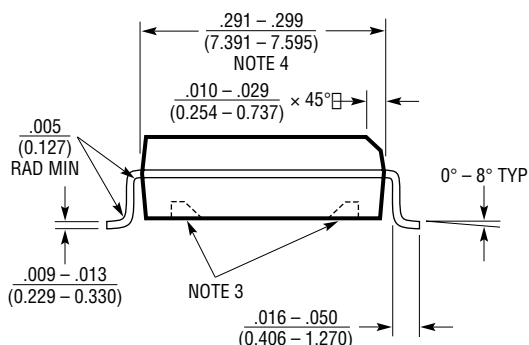
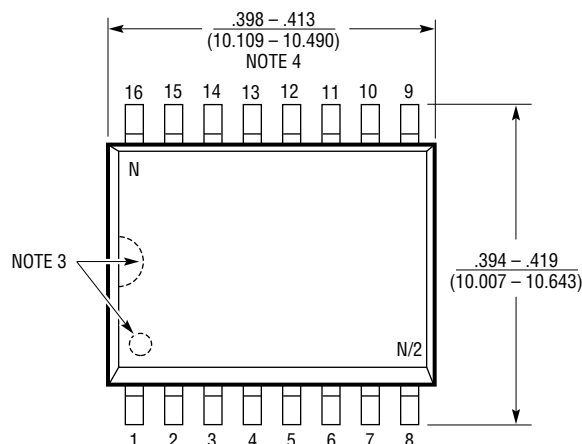
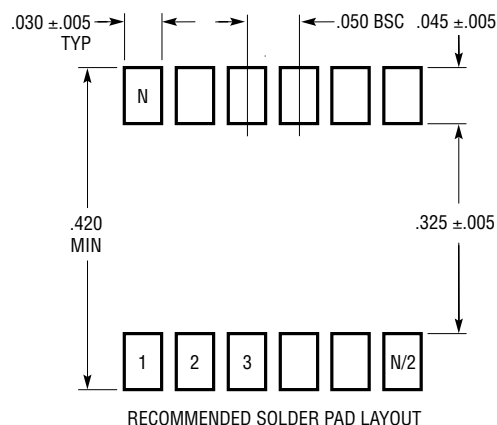
NOTE:
1. DIMENSIONS ARE $\frac{\text{INCHES}}{\text{MILLIMETERS}}$

*THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 INCH (0.254mm)

N14 1002

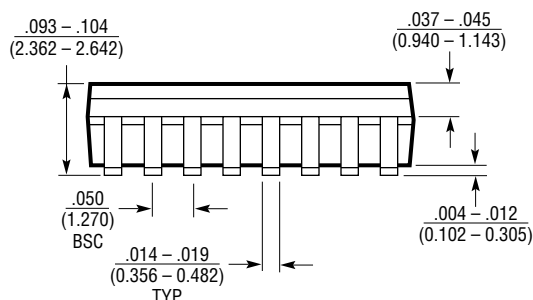
PACKAGE DESCRIPTION

SW Package 16-Lead Plastic Small Outline (Wide .300 Inch) (Reference LTC DWG # 05-08-1620)



NOTE:

1. DIMENSIONS IN $\frac{\text{INCHES}}{\text{MILLIMETERS}}$
2. DRAWING NOT TO SCALE
3. PIN 1 IDENT, NOTCH ON TOP AND CAVITIES ON THE BOTTOM OF PACKAGES ARE THE MANUFACTURING OPTIONS. THE PART MAY BE SUPPLIED WITH OR WITHOUT ANY OF THE OPTIONS
4. THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006" (0.15mm)



S16 (WIDE) 0502